

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	148	(solder) same (powder) same (volume or "vol.") near2 (percent \$4 or percentage or "%")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:52
L2	79	1 and (flux)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:52
L3	80	1 and (flux\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:52
L4	17	(US-20040190252-\$ or US-20040016995-\$ or US-20040227236-\$ or US-20100038123-\$ or US-20090289101-\$ or US-20050093153-\$ or US-20030121564-\$).did. or (US-6454159-\$ or US-6189771-\$ or US-6736907-\$ or US-6641679-\$ or US-5834848-\$ or US-5869904-\$ or US-6111322-\$ or US-6122177-\$ or US-6166433-\$).did. or (JP-2003264259-\$).did.	US-PGPUB; USPAT; DERWENT	ADJ	ON	2011/09/28 15:53
L5	300	("3871015"   "4684544"   "4921550"   "5012502"   "5040281"   "5216278"   "5233504"   "5276289"   "5355019"   "5371404"   "5417771"   "5455457"   "5473512"   "5485949"   "5533256"   "5535101"   "5569960"   "5585671"   "5598036"   "5640051"   "5641996"   "5658827"   "5705850"   "5729440"   "5731630"   "5751060"   "5762258"   "5764485"   "5773888"   "5804248"   "5866951"   "5877079"   "5878943"   "5904782"   "5905636"   "5932345"   "5950908"   "5953592"   "5973337"   "5973406"   "5985695"   "5989362"   "5990545"   "6025258"   "6030889"   "6059894"   "6090301"   "6132543"   "6189771"   "Re35423").PN. OR ("2003/0121564"   "2004/0016995"   "2004/0190252"   "2004/0227236"   "2005/0093153"   "2009/0289101"   "2010/0038123"   "5834848"   "5869904"   "6111322"	US-PGPUB; USPAT; USOCR	ADJ	ON	2011/09/28 15:53

		"6122177"   "6166433"   "6189771"   "6454159"   "6641679"   "6736907").URPN.				
L6	1273	(228/214,215,256).CQLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2011/09/28 15:56
L7	179	6 and (powder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:56
L8	70	7 and (volume or vol or "vol.")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/28 15:56
S1	1	("20080048009").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/08/17 09:59
S2	4	((("6199771") or ("6680128") or ("6951666") or ("5837119"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/08/17 10:05
S3	99	(particle or particulate or powder) with (flake) with solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:09
S4	17	(resin or epoxy) with (coat\$3 or layer or film) same (particle or particulate or powder) with (flake) same solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:21
S5	67	(resin or epoxy or polymer\$3) with (flake) with (metal\$4) same solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:28
S6	13513	(resin or epoxy or polymer\$3) with (coat\$3 or layer or film) with (solder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:45
S7	75	S6 same (flake or flat) with (metal \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/17 10:46
S8	2641	bent with circuit board same (solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:09
S9	82	bent with circuit board same (solder\$3) ball	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:09
S10	21	bent with component same (solder \$3) ball	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:11
S11	528	(various or different) with (siz\$3 or diameter) with (solder\$3 near (ball or bump))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:12
S12	200	(various or different) with (siz\$3 or diameter) with (solder\$3 near (ball or bump)) same substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:12
S13	3	("2004/0227236").URPN.	USPAT	ADJ	ON	2011/01/25 20:15

S14	36	( bent or curv\$3) with component same (solder\$3) ball	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:19
S15	50	(warp\$3) with component same (solder\$3) ball	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:22
S16	15	"6189771"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:35
S17	10	("20040177997"   "5234149"   "5672542"   "6121062"   "6189771"   "6297560"   "6495397"   "6566234"   "7244634").PNL OR ("7632710"). URPNL	US-PGPUB; USPAT; USOCR	ADJ	ON	2011/01/25 20:36
S18	15	"6189771"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:40
S19	591	flux same (iminodiacetic acid or \$3hydroxybenzoic acid or \$3phenylalanine or mesaconic acid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:46
S20	59	flux with (iminodiacetic acid or \$3hydroxybenzoic acid or \$3phenylalanine or mesaconic acid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/25 20:47
S21	1	("6,680,128").PNL	US-PGPUB; USPAT; USOCR	OR	OFF	2011/01/26 16:14
S22	63	flux same (\$4hydroxy\$1benzoic near acid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 16:22
S23	2	"20080048009"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 16:53
S24	13067	solder (bump or ball) same (electrodes)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 17:02
S25	1292	solder (bump or ball) same (electrodes) same(bga)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 17:03
S26	1292	solder (bump or ball) same (electrodes) same (bga)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 17:03
S27	105	(bga or semiconductor) same (solder near2 (ball or bump)) with (various or different) near2 (size or diameter)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 17:24

S28	1	"10585729"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/01/26 19:02
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**EAST Search History (Interference)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L9	4156	((228/111.5,208,262.45,214,215,256) or (438/612)). CCL.S.	US- PGPUB; USPAT; UPAD	OR	OFF	2011/09/28 16:18
L10	0	9 and ((solder\$3) and (method or process) and (electrode) and (melt\$4) and (coat\$3 or layer or film \$3) with (paste) and (resin) and (flake or oblong or oval) near2 (shap\$4) and (core near2 metal) and (solidif\$4)).clm.	US- PGPUB; USPAT; UPAD	ADJ	ON	2011/09/28 16:20

9/ 28/ 2011 4:20:55 PM

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